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Global TGV (Through Glass Via) Foundry Market 2026 by Company, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global TGV (Through Glass Via) Foundry market size was valued at US$ 152 million in 2025 and is forecast to a readjusted size of US$ 489 million by 2032 with a CAGR of 18.4% during review period.

Through-glass via (TGV) foundry refers to the process of making tiny vertical through holes (usually with a diameter of 10?m~100?m) on high-quality borosilicate glass or quartz glass substrates through a series of high-precision processes, and filling these through holes with conductive materials (such as copper) to achieve electrical connections. This technology uses laser etching, inductively coupled plasma dry etching and other methods to prepare through holes. It has the advantages of excellent high-frequency electrical properties, strong mechanical stability, low cost, and simple process flow. It has broad application prospects in the fields of precision devices such as Mini/Micro LED direct display and semiconductor advanced packaging substrates. In 2024, global TGV Substrate production reached approximately 4,000 K Pcs, with an average global market price of around US$ 30 per piece.

TGV substrates exhibit excellent high-frequency electrical properties. The dielectric constant of glass is approximately one-third that of silicon, and the dissipation factor is two to three orders of magnitude lower than silicon. This significantly reduces substrate losses and parasitic effects, ensuring signal integrity. TGV substrate production eliminates the need for complex insulating layer deposition processes, and thinning is not required in the ultra-thin interposer, streamlining the production process and improving efficiency. Due to the readily available availability of large-scale, ultra-thin panel glass and the elimination of the need for insulating layer deposition on the substrate surface or the inner walls of the TGV, production costs are significantly

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reduced. Even with an interposer thickness less than 100?m, warpage remains minimal, ensuring the stability and reliability of the package structure. TGV substrates offer unique advantages in applications such as RF chips, high-end MEMS sensors, and high-density system integration, making them a preferred choice for next-generation high-frequency chip 3D packaging.

The Through Glass Via (TGV) foundry market is entering a rapid growth phase, driven by demand for high-density interconnects in advanced packaging, photonics, MEMS, and RF modules. Over the next five years, adoption will accelerate as TGV technology enables superior electrical performance, thermal stability, and miniaturization compared to traditional substrates. Asia?especially China, Japan, and South Korea?is expected to lead in scaling production capacity, while North America and Europe focus on high-reliability and defense-related applications. With its high technical barriers and expanding use in 2.5D/3D integration, the TGV foundry segment is projected to achieve strong profitability as yield, automation, and panel-level processing improve.

This report is a detailed and comprehensive analysis for global TGV (Through Glass Via) Foundry market. Both quantitative and qualitative analyses are presented by company, by region & country, by Size and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global TGV (Through Glass Via) Foundry market size and forecasts, in consumption value ($ Million), 2021-2032

Global TGV (Through Glass Via) Foundry market size and forecasts by region and country, in consumption value ($ Million), 2021-2032

Global TGV (Through Glass Via) Foundry market size and forecasts, by Size and by Application, in consumption value ($ Million), 2021-2032

Global TGV (Through Glass Via) Foundry market shares of main players, in revenue ($ Million), 2021-2026

The Primary Objectives in This Report Are:

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To determine the size of the total market opportunity of global and key countries

To assess the growth potential for TGV (Through Glass Via) Foundry

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global TGV (Through Glass Via) Foundry market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Corning, Samtec, Plan Optik, Vitrion (LPKF), WOP, E&R, Kiso Micro, 3D Glass Solutions, Nanosystems, NSC, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market segmentation

TGV (Through Glass Via) Foundry market is split by Size and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for Consumption Value by Size and by Application. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Size

300mm

200mm

?150mm

Market segment by Type

Panel-Level TGV Substrate

Wafer-Level TGV Substrate

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Market segment by Metallization Methods

- Electroplated Copper Filling
- Sputtering Metallization
- Nanometallic Slurry Filling

Market segment by Application

- Consumer Electronics
- Automotive Industry
- Others

Market segment by players, this report covers

- Corning
- Samtec
- Plan Optik
- Vitrion (LPKF)
- WOP
- E&R
- Kiso Micro
- 3D Glass Solutions
- Nanosystems

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NSC

NICHIWA KOGYO

Sky Semiconductor

Jiangxi Woge Optoelectronics

Chengdu Micro-Technology

Hubei W-OLF PHOTOELECTRIC Technology

Sai MicroElectronics

Zhejiang Lante Optics

Suzhou Senwan Electronics Technology

Group Up Industrial

Market segment by regions, regional analysis covers
North America (United States, Canada and Mexico)
Europe (Germany, France, UK, Russia, Italy and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia and Rest of Asia-Pacific)

South America (Brazil, Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe TGV (Through Glass Via) Foundry product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of TGV (Through Glass Via) Foundry, with

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revenue, gross margin, and global market share of TGV (Through Glass Via) Foundry from 2021 to 2026.

Chapter 3, the TGV (Through Glass Via) Foundry competitive situation, revenue, and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Size and by Application, with consumption value and growth rate by Size, by Application, from 2021 to 2032.

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2021 to 2026.and TGV (Through Glass Via) Foundry market forecast, by regions, by Size and by Application, with consumption value, from 2027 to 2032.

Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of TGV (Through Glass Via) Foundry.

Chapter 13, to describe TGV (Through Glass Via) Foundry research findings and conclusion.

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Materials)

Table 146. Global TGV (Through Glass Via) Foundry Typical Customers

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